

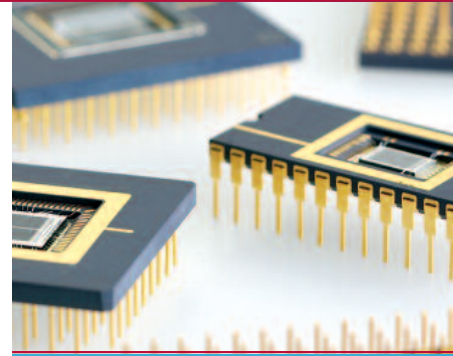
# Back-End Services

## Wafer probe, assembly and test

MHS Electronics has chosen to offer partnership contracts for back-end manufacturing: **Wafer Probing, IC Assembly, Final Test, Quality and Reliability Services.**

MHS is ideally positioned to support any IC manufacturer back-end activity for demanding customers in terms of flexibility, hi-reliability and security.

MHS is also fully equipped to manage customer testers consigned at our Nantes location (France).



“ Back-End added value is a major contributor to the final Quality of Hi-Rel products ”

## Hi-Reliability orientation, experience and focus

- MHS, which is the partner of choice for most European electronic actors in the Military and Aerospace markets, has developed a strong reputation in managing back-end activities for Hi-Reliability products.
- Demanding markets such as Biomedical or Automotive are also welcome into our back-end facility.
- With full qualification to ISO/TS 16949, ISO 14001, and into an active roadmap to EN 9100 (Aerospace), DSCC lab-suitability (US Military Std) and ISO 13485 (Medical), MHS is committed to the highest levels of quality and service.

## Secured environment

MHS has developed and already implemented every security precaution to accept “secured & classified products”.

Safe storage facilities are available to ensure confidentiality to customer needs (national security, banking...)

Wafer Probing	Assembly (*)	Test and Services
6 & 8" wafer diameter 25 to 125°C	Plastic for mid and high volume (Asia)	Functional package test at 3 temperatures (-55, 25, 125°C)
Off-line inking or wafer-map data files	Ceramic for low volume, Hi-Quality (Europe)	Burn-in & mechanical tests for Mil & Space ceramic packages
Class ISO 5/6 clean room		Full logistics service with customer source inspection if needed

(\*) Although MHS has no in-house assembly line, the experience in assembly techniques and the relationships with all back-end qualified partners assure an excellent level of project control, confidence and efficiency.

# List of Equipment & Services

## WAFER PROBE

- Electroglass 4090µ 6 & 8 inch wafer size probers
- KLA 1007 6 inch probers for off-line inking

## PACKAGE TEST (\*)

- Schlumberger ITS9000 (196 IO's - 40Mhz)
- Schlumberger Sentry 15 (256 IO's - 20Mhz)
- HP 83000 (448 IO's - 80Mhz)
- Maverick GT512 (512 IO's - 33Mhz)
- Maverick PT64 (64 IO's - 33Mhz)
- Megatest Q2/62 (40 IO's - 10Mhz)
  
- Aetrium 1400T automatic pick & place handler
- Tempronics temperature conditioners

(\*) new mixed signal A/D testers are coming soon

## BURN-IN AND MEASURING

- Burn-in Reliability Criteria 4 & 5
- Mechanical tests (package test) of Mil Std group B/ ESCC LAT3

## BUILDING AND FACILITIES

- Total area of 1300 sqm of ESD safe building
- Available 500 sqm for customer's consigned equipment
- Temperature and relative humidity controlled in real time 24/24
- Class ISO 5/6 clean room for wafer sort activity (300 sqm)
- Waste disposal management
- All facility fluid services available (N<sub>2</sub>, O<sub>2</sub>, DI water, CDA, cooling water, UPS...)
- All building fully secured for high level security

## PRODUCTION AND LOGISTICS SUPPORT

Real time "in-line" data are available through MHS FOCUS Extranet application, 24/24 & 7/7:

- Production items as WIP data
- Wafer probe and test results
- Quality and inspection documents are shown using FOCUS



MHS is also pleased to welcome those customers who would like to place their equipment (testers and/or burn-in) in consignment at the Nantes facility (France).

You will find excellent support, production control, logistics, maintenance equipment, short cycle time and competitive pricing for your test requirements.



**Contact:**  
[founry@mhs-electronics.com](mailto:founry@mhs-electronics.com)

